

## Electrical characteristics

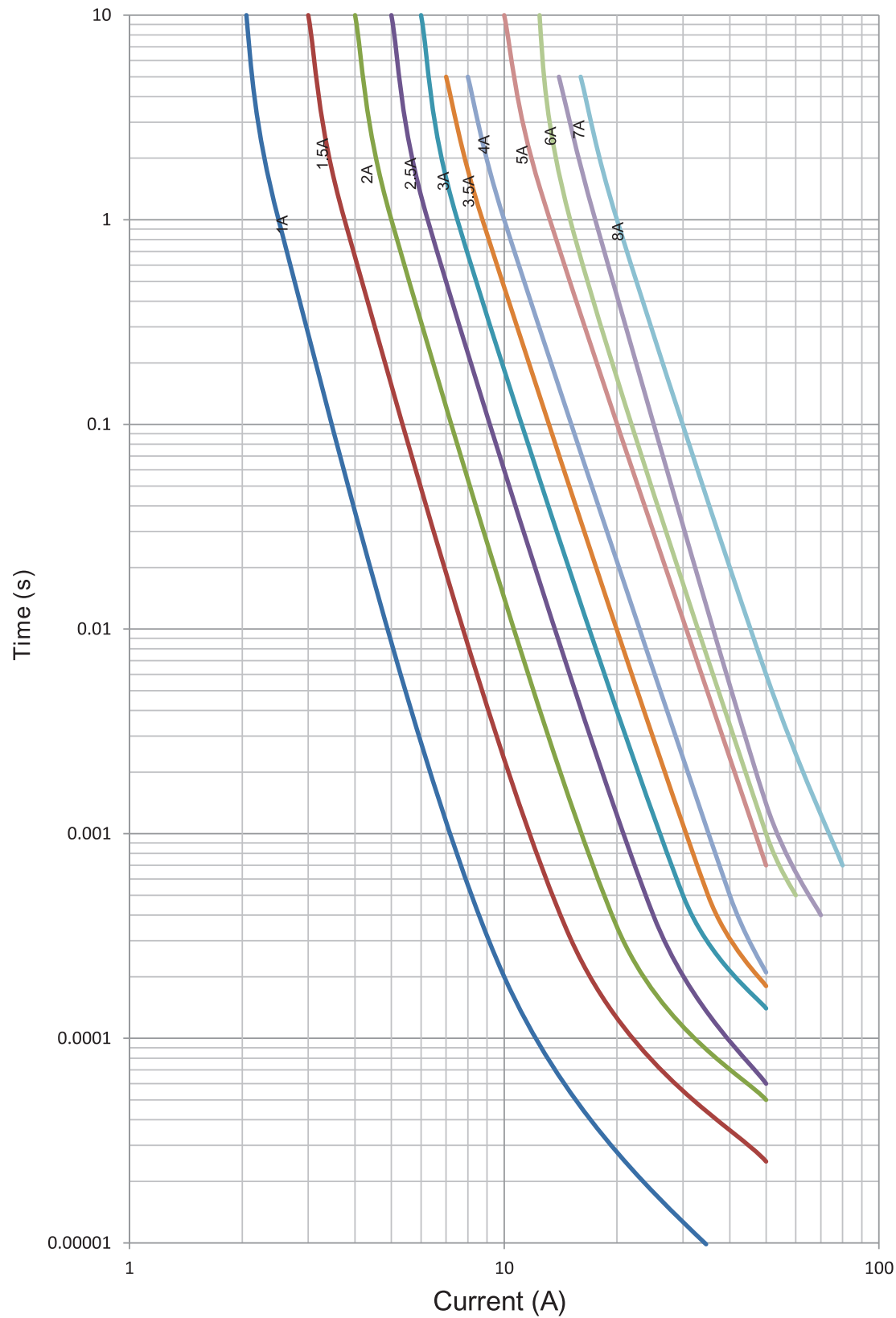
Amp Rating	% of Amp Rating	Opening Time
1-8 A	100	4 Hours
1-7 A	200	1-60 Seconds
1-8 A	250	5 Seconds Max

## Specifications

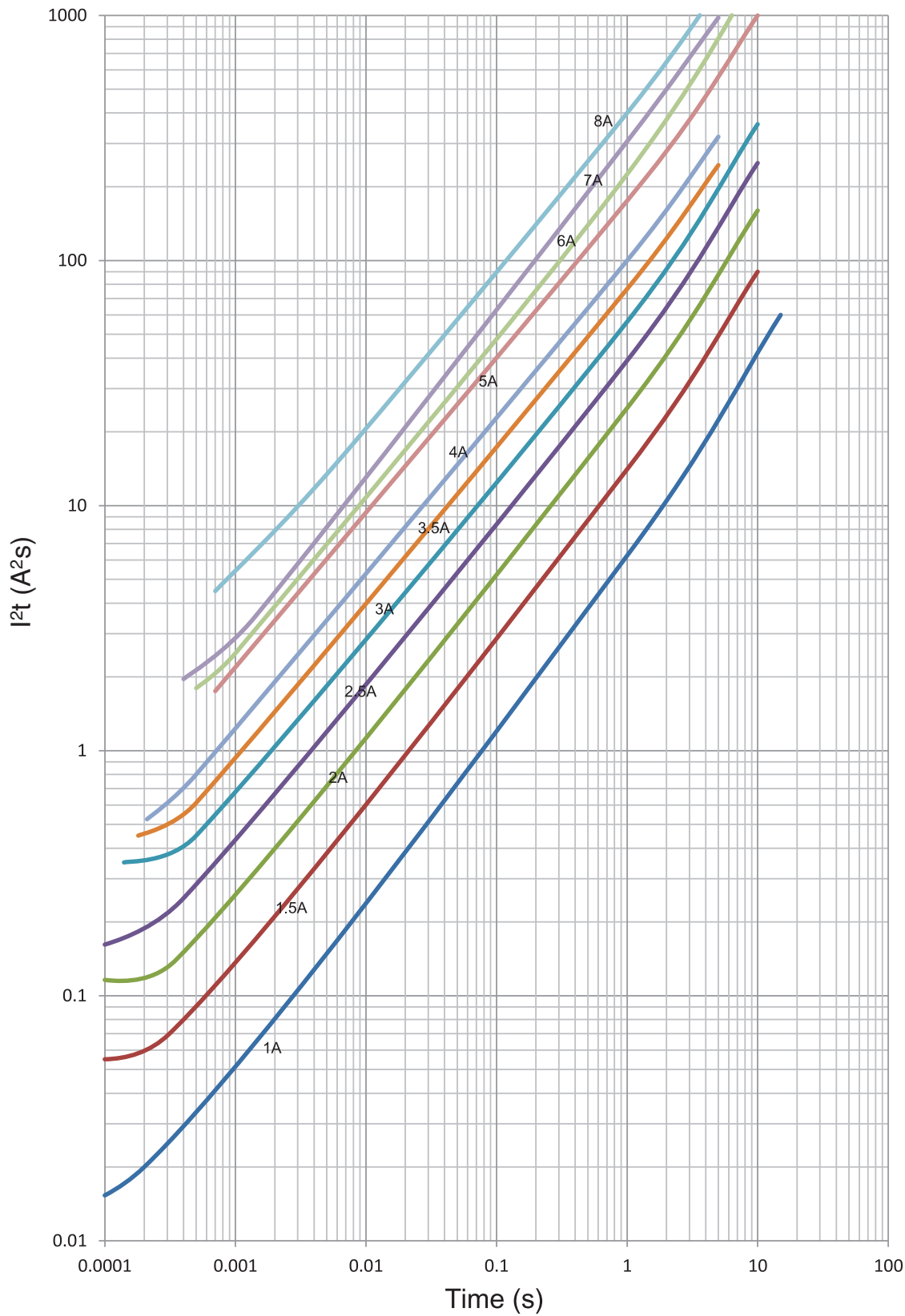
Part Number	Amp Rating <sup>5</sup>	Voltage Rating (Vdc)	Interrupting Rating <sup>1, 4</sup> (A)	Typical Cold Resistance <sup>2</sup> (Ω)	Typical Pre-Arcing <sup>3</sup> (I <sup>2</sup> t)	Typical Voltage Drop (mV)	Typical Power Dissipation (W)	Alpha Marking	Agency Information (cURus)
CC06H1A	1	32	50	0.25	0.02	310	0.32	B	x
CC06H1.5A	1.5	32	50	0.13	0.07	250	0.38	H	x
CC06H2A	2	32	50	0.068	0.14	170	0.38	K	x
CC06H2.5A	2.5	32	50	0.05	0.25	155	0.38	L	x
CC06H3A	3	32	50	0.035	0.30	130	0.38	O	x
CC06H3.5A	3.5	32	50	0.023	0.50	100	0.35	R	x
CC06H4A	4	32	50	0.02	0.8	110	0.45	S	x
CC06H5A	5	32	50	0.013	1.6	95	0.48	T	x
CC06H6A	6	32	50	0.0076	2.6	80	0.48	V	x
CC06H7A	7	32	50	0.0056	3.3	80	0.56	X	x
CC06H8A	8	32/24	50/80	0.0040	4.5	75	0.60	Z	x

1. DC Interrupting Rating (measured at rated voltage, time constant of less than 50 microseconds, battery source).
2. DC Cold Resistance are measured at <10% of rated current in ambient temperature of 20 °C -  
FOR REFERENCE ONLY - CONTROLLED VALUES HELD BY PLANT AND SUBJECT TO CHANGE WITHOUT NOTICE.
3. Typical Pre-arcing I<sup>2</sup>t are measured at rated DC voltage, 10I<sub>n</sub> current (not to exceed interrupting rating).
4. The insulation resistance after breaking capacity test is higher than 0.1 MΩ when measured by 2X rated voltage.
5. Device designed to carry rated current for 4 hours minimum. An operating current 80% or less of rated current is recommended, with further design derating required at elevated ambient temperature. See Temperature Derating Curve on next page.

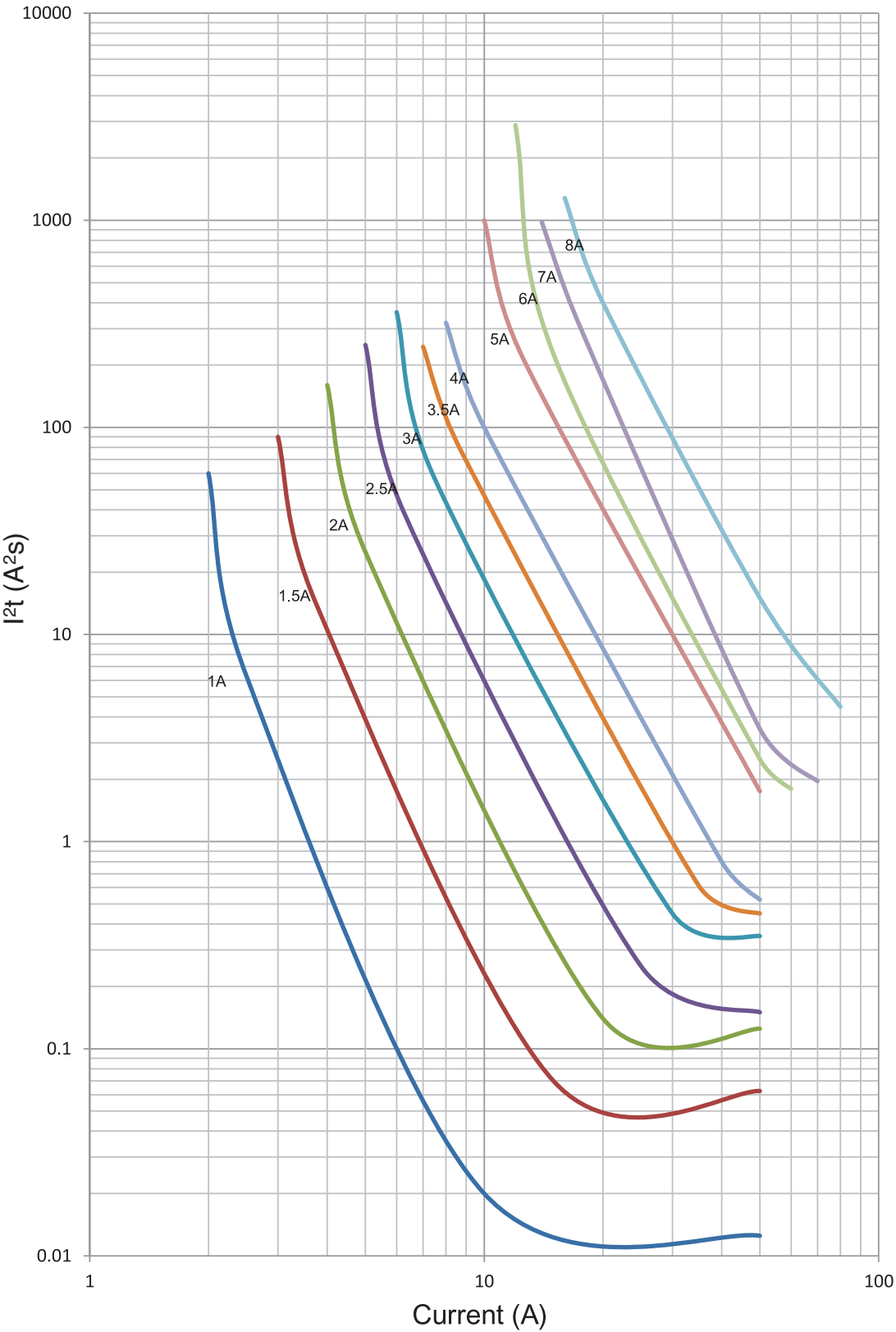
Time-current curves — average melt



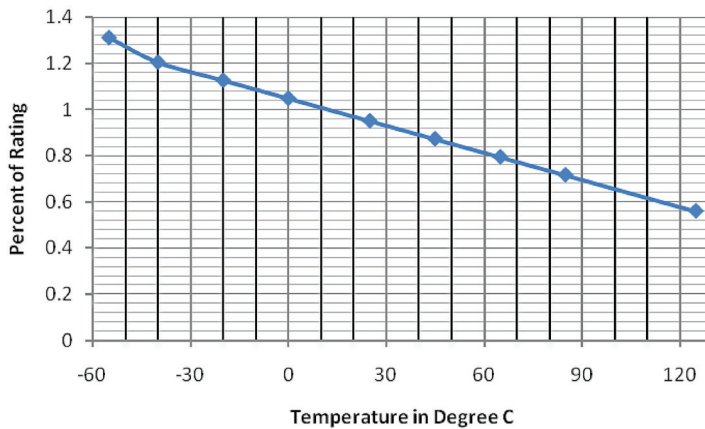
I<sup>2</sup>t vs. time curves



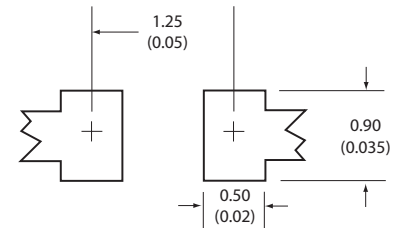
I<sup>2</sup>t vs. current curves



### Temperature derating curve

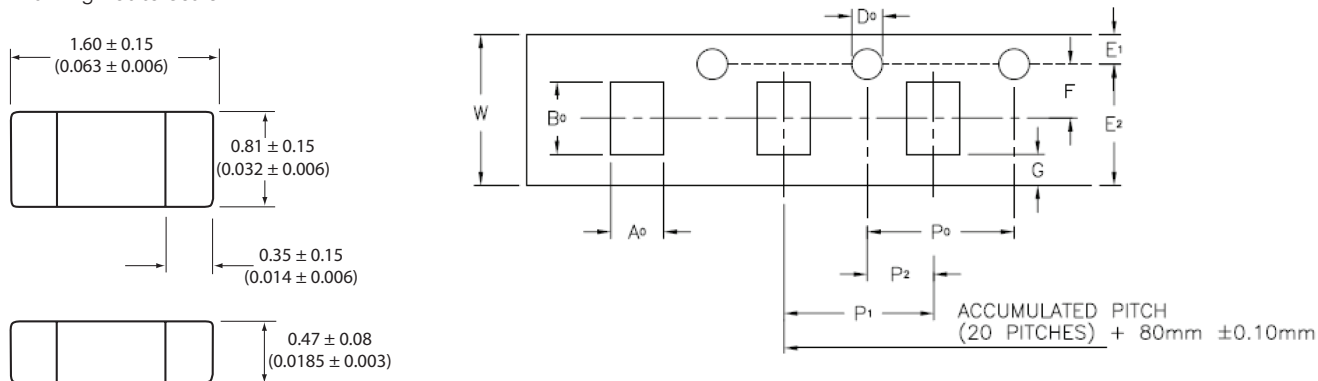


### Pad layout



### Dimensions - mm (in)

Drawing not to scale.



A <sub>0</sub>	B <sub>0</sub>	D <sub>0</sub>	E <sub>1</sub>	E <sub>2</sub>	F	G	P <sub>0</sub>	P <sub>1</sub>	P <sub>2</sub>	T	W
0.95 ±0.05	1.80 ±0.05	1.50 +0.10, -0.0	1.75 ±0.10	6.25 ±0.30	3.50 ±0.05	0.75 min.	4.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.060 ±0.05	8.00 ±0.20

### Product characteristics

Operating temperature	-40 °C to +85 °C , with proper derating factor applied
Storage temperature	-40 °C to +85 °C
Load humidity	MIL-STD-202G, Method 103B (1000 hr @ +85 °C / 85% RH & 10% rated current)
Moisture resistance	MIL-STD-202, Method 106E (50 cycles)
Thermal shock	MIL-STD-202, Method 107D (-65 °C to +125 °C, 100 cycles)
Vibration test	MIL-STD-202, Method 204D, Test Condition D (10-2,000 Hz)
Mechanical shock resistance	MIL-STD-202, Method 213B (3000 G / 0.3 ms)
Salt spray resistance	MIL-STD-202, Method 101, Test Condition B (48 hour exposure)
Insulation resistance	The insulation resistance after breaking capacity test is higher than 0.1MΩ when measured by 2X rated voltage
Solderability	J-STD-002C Method B1 (Dip and Look Test), Method G1 (Wetting Balance Test), Method D (Resistance to Dissolution / Dewetting of Metalization)
Resistance to soldering heat	MIL-STD-202, Method 210F (Solder dip +260 °C, 60 seconds / Solder Iron +350 °C, 3-5 seconds)
High temperature life test	MIL-STD-202G, Method 108A (1000 Hours @ +70 °C & 60% rated current)
Resistance to solvents	MIL-STD-202, Method 215K

## Solder reflow profile

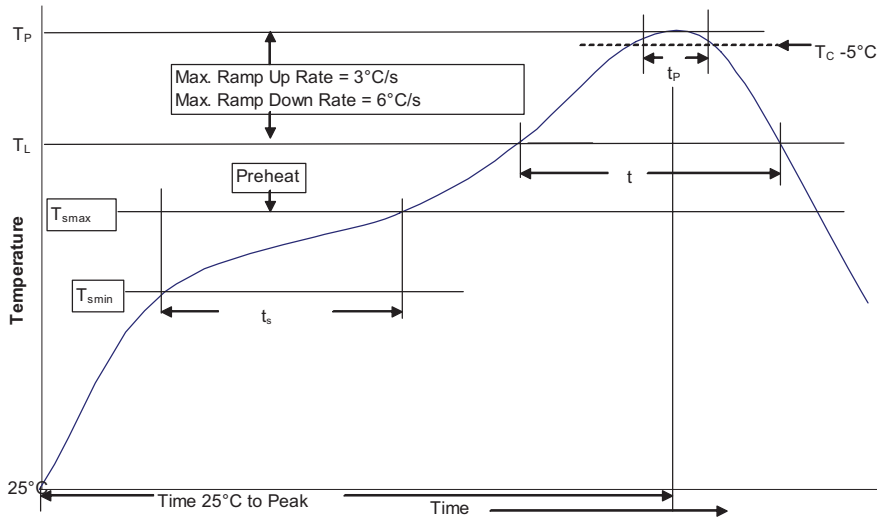


Table 1 - Standard SnPb Solder ( $T_C$ )

Package Thickness	Volume $\leq 350$ mm <sup>3</sup>	Volume $\geq 350$ mm <sup>3</sup>
<2.5mm	235°C	220°C
$\geq 2.5$ mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder ( $T_C$ )

Package Thickness	Volume $\leq 350$ mm <sup>3</sup>	Volume 350 - 2000 mm <sup>3</sup>	Volume $> 2000$ mm <sup>3</sup>
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

## Reference JEDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. ( $T_{smin}$ )	100°C	150°C
• Temperature max. ( $T_{smax}$ )	150°C	200°C
• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 Seconds	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_P$	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature ( $T_L$ )	183°C	217°C
Time at liquidous ( $t_L$ )	60-150 Seconds	60-150 Seconds
Peak package body temperature ( $T_P$ )*	Table 1	Table 2
Time ( $t_p$ )** within 5 °C of the specified classification temperature ( $T_C$ )	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_P$ to $T_{smax}$ )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature ( $T_P$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

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Printed in USA  
Publication No. 4346 BU-SB14476  
June 2017

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